

REMARKS/ARGUMENTS

Claims 1 and 5-21 have been amended, new claims 22-25 have been added, and claims 1-25 now are pending in this application. No new matter has been added.

1. Objection to the Disclosure

The disclosure stands objected to because, at page 5, paragraph 13, updated status information for the cited co-pending application should be provided, if available.

In response, Applicants have now amended paragraph 13 to identify the recently issued patent of Casey, which is U.S. Patent No. 6,953,698. Accordingly, the specification is believed to be allowable.

2. Objection to the Disclosure

The disclosure stands objected to because, at page 6, paragraph 15, second line therein, the word --respective-- should precede "first" and "second" for clarity of description.

In response, Applicants have now amended paragraph 15 to insert the word --respective-- prior to the word "first" and prior to the word "second" as suggested by the Examiner. Accordingly, the specification is believed to be allowable.

3. Objection to the Disclosure

The disclosure stands objected to because, at page 6, paragraphs 15 and 17, the reference labels therein should be associated with appropriate ones of FIGS. 1 and 2 in which they are depicted.

In response, Applicants have now amended paragraphs 15 and 17 to more clearly identify the relationship of the reference numerals and the figure numbers. Accordingly, the specification is believed to be allowable.

4. Objection to the Disclosure

The disclosure stands objected to because, at pages 7 and 8, paragraphs 21 and 22, the following recitations should be rewritten for clarity: "cutting 402", "mounted 404", "placed 408", "selected 502", "mounted 504", "coupled 506", and "placed 508".

In response, Applicants have now amended paragraphs 21 and 22 to more clearly identify the above-identified recitations. Accordingly, the specification is believed to be allowable.

5. Objection to the Drawings

The drawings stand objected to under 37 CFR 1.83(a) because the drawings must show every feature of the invention specified in the claims.

In response, Applicants respectfully traverse the Examiner's objection inasmuch as the bridge connector 310 in FIG. 3 represents the features of the ribbon bond, the mesh bond, and the plurality of wire bonds. Accordingly, the drawings are believed to be allowable.

6. Rejection of Claims 5-8 Under 35 U.S.C. 112, Second Paragraph

Claims 5-8 stand rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

Claims 5 and 6 have now been amended to change "the second ground shields" to -- the ground shield of each of the microwave modules --. Accordingly, claims 5 and 6 are believed to be in condition for allowance, and allowance thereof is respectfully requested.

Claim 7 has now been amended to change "the substrate of each microwave module comprises ceramic" and to -- each of the microwave modules comprises a ceramic substrate --. Accordingly, claim 7 is believed to be in condition for allowance, and allowance thereof is respectfully requested.

Claim 8 has now been amended to change "first and second dielectrics" to -- upper and lower thickfilm dielectrics --. Accordingly, claim 8 is believed to be in condition for allowance, and allowance thereof is respectfully requested.

7. Objection to Claims 9, 10 and 16

Claims 9, 10 and 16 stand objected to inasmuch as a --:-- should follow "comprising" for a proper characterization.

In response, Applicants respectfully traverse the Examiner's objection and assert that each one of claims 9, 10 and 16 as originally filed include a colon after the word "comprising". In claims 9 and 16, a colon is after the word "comprising" at the end of the first line. In claim 10, as amended, a colon is after the word "comprising" at the end of line 10. Accordingly, Applicants respectfully request reconsideration in that claims 9, 10 and 16 are believed to be allowable. However, if this is incorrect, further clarification is respectfully requested.

8. Objection to Claims 11-15 and 17-21

Claims 11-15 and 17-21 stand objected to as these claims each depend from an independent claim in the format of a method claim.

In response, Applicants have now amended claims 11-15 and 17-21 to provide each of these claims in the format of a method claim. Accordingly, claims 11-15 and 17-21 are believed to be allowable.

9. Rejection of Claim 1 Under 35 U.S.C. 102(b)

Claims 1 stands rejected under 35 U.S.C. 102(b) as being anticipated by Ishihara (Japanese Patent No. 92102; hereinafter "Ishihara").

Independent claim 1, as amended, calls for a microwave circuit comprising first and second microwave modules, each of which comprises a conductor sandwiched between upper and lower thickfilm dielectrics, and a ground shield surrounding the upper and lower thickfilm dielectrics in a direction transverse to the conductor; wherein, at a first end of each of the conductors, the conductor extends from beneath its upper thickfilm dielectric to terminate at a cut edge of its microwave module; the microwave modules being mounted with said cut edges facing one another; a bridge conductor, electrically coupling the first ends of the conductors; and a ground shield cap, oriented over the bridge conductor and electrically coupled to the ground shield surrounding the upper and lower thickfilm dielectrics of each of the microwave modules.

Applicants believe that Ishihara does not disclose or suggest a ground shield that surrounds upper and lower thickfilm dielectrics and the conductor. Applicants believe that Ishihara does not disclose a ground shield cap that is electrically coupled to a ground shield surrounding upper and lower thickfilm dielectrics. Applicants believe that Ishihara discloses layers of metallization on dielectric layers; however, the layers of metallization do not surround the center conductor as the sides of the layers metallization are unconnected. Accordingly, claim 1 is believed to be in condition for allowance, and allowance thereof is respectfully requested.

Claims 2-8, which depend directly from independent claim 1, are believed to be in condition for allowance for at least the above-identified reasons. Accordingly, allowance of claims 2-8 is respectfully requested.

10. Rejection of Claims 9, 10 and 16 Under 35 U.S.C. 103(a)

Claims 9, 10 and 16 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Ishihara in view of the IBM Technical Disclosure Bulletin.

Independent claim 9, as amended, calls for a microwave circuit, comprising first and second microwave modules, each comprising i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; wherein, for each microwave module, at least the second dielectric and second ground shield are recessed from an end of the conductor terminating at or near a cut edge of the microwave module; wherein, for each microwave module, the first ground shield and the second ground shield contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor; the microwave modules being mounted with said cut edges facing one another; a bridge conductor, electrically coupling said ends of the conductors of the microwave modules; and a ground shield cap, oriented over the bridge conductor and electrically coupled to the second ground shield of each of the microwave modules.

Applicants believe that neither Ishihara nor the IBM Technical Disclosure Bulletin disclose or suggest a first ground shield and a second ground shield that surround the first dielectric and the second dielectric. Applicants believe that neither Ishihara nor the IBM Technical Disclosure Bulletin disclose or suggest a ground shield cap that is electrically coupled to the second ground shield of each of the microwave modules. Applicants believe that the IBM Technical Disclosure Bulletin discloses a bridging strip for establishing a connection between two ground plan coatings on the surfaces of substrates. Applicants believe that Ishihara discloses layers of metallization on dielectric layers; however, the layers of metallization do not surround the center conductor as the sides of the layers metallization are unconnected. Accordingly, claim 9 is believed to be in condition for allowance, and allowance thereof is respectfully requested.

Independent claim 10, as amended, calls for a method for coupling first and second microwave modules, wherein each microwave module comprises i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; and wherein, for each microwave module, at least the second dielectric and second ground shield are recessed from a first end of the conductor;

wherein, for each microwave module, the first ground shield and the second ground shield contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor; the method comprising for each of the microwave modules, cutting the microwave module in proximity to the first end of the conductor, thereby defining a first edge of the microwave module; mounting the microwave modules adjacent one another, with their first edges facing each other; electrically coupling said first ends of the conductors of the microwave modules; and placing a ground shield cap over the conductor coupling, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules.

Applicants believe that neither Ishihara nor the IBM Technical Disclosure Bulletin disclose or suggest a method for coupling first and second microwave modules, comprising a first ground shield and a second ground shield that contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules. Applicants believe that the IBM Technical Disclosure Bulletin discloses the use of a bridging strip for establishing a connection between two ground plan coatings on the surfaces of substrates. Applicants believe that Ishihara discloses the use of layers of metallization on dielectric layers; however, the layers of metallization do not surround the center conductor as the sides of the layers metallization are unconnected. Accordingly, claim 10 is believed to be in condition for allowance, and allowance thereof is respectfully requested.

Independent claim 16, as amended, calls for a method, comprising selecting first and second microwave modules, each comprising i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; wherein, for each microwave module, at least the second dielectric and second ground shield are recessed from an end of the conductor terminating at or near a cut edge of the microwave module; wherein, for each microwave module, the first ground shield and the second ground shield contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor; mounting the microwave modules adjacent one another, with said cut edge of the first microwave module

facing said cut edge of the second microwave module; electrically coupling said ends of the conductors of the microwave modules; and placing a ground shield cap over the conductor coupling, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules.

Applicants believe that neither Ishihara nor the IBM Technical Disclosure Bulletin disclose or suggest a method comprising the first ground shield and the second ground shield contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules. Applicants believe that the IBM Technical Disclosure Bulletin discloses the use of a bridging strip for establishing a connection between two ground plan coatings on the surfaces of substrates. Applicants believe that Ishihara discloses the use of layers of metallization on dielectric layers; however, the layers of metallization do not surround the center conductor as the sides of the layers metallization are unconnected. Accordingly, claim 16 is believed to be in condition for allowance, and allowance thereof is respectfully requested.

11. Rejection of Claims 2 and 4 Under 35 U.S.C. 103(a)

Claims 2 and 4 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Ishihara in view of Cox et al. (U.S. Patent No. 6,100,774; hereinafter "Cox et al.").

Claims 2 and 4 each depend directly from independent claim 1. As discussed hereinabove, independent claim 1 calls for a microwave circuit comprising first and second microwave modules, each of which comprises a conductor sandwiched between upper and lower thickfilm dielectrics, and a ground shield surrounding the upper and lower thickfilm dielectrics in a direction transverse to the conductor; wherein, at a first end of each of the conductors, the conductor extends from beneath its upper thickfilm dielectric to terminate at a cut edge of its microwave module; the microwave modules being mounted with said cut edges facing one another; a bridge conductor, electrically coupling the first ends of the conductors; and a ground shield cap, oriented over the bridge conductor and electrically coupled

to the ground shield surrounding the upper and lower thickfilm dielectrics of each of the microwave modules.

Applicants believe that neither Ishihara nor Cox et al. disclose or suggest a ground shield that surrounds upper and lower thickfilm dielectrics and the conductor, and do not disclose or suggest a ground shield cap that is electrically coupled to a ground shield surrounding upper and lower thickfilm dielectrics. Inasmuch as claim 1 is believed to be in condition for allowance, claims 2 and 4 are believed to be in condition for at least those reasons. Accordingly, allowance of claims 2 and 4 is respectfully requested.

12. Rejection of Claims 11, 13, 17 and 19 Under 35 U.S.C. 103(a)

Claims 11, 13, 17 and 19 stand rejected under 35 U.S.C. 103(a) as being unpatentable over the rejection of Item 4 above as applied to claims 10 and 16, and further in view of Cox et al.

Claims 11 and 13 depend directly from independent claim 10. As discussed above, independent claim 10 calls for a method for coupling first and second microwave modules, wherein each microwave module comprises i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; and wherein, for each microwave module, at least the second dielectric and second ground shield are recessed from a first end of the conductor; wherein, for each microwave module, the first ground shield and the second ground shield contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor; the method comprising for each of the microwave modules, cutting the microwave module in proximity to the first end of the conductor, thereby defining a first edge of the microwave module; mounting the microwave modules adjacent one another, with their first edges facing each other; electrically coupling said first ends of the conductors of the microwave modules; and placing a ground shield cap over the conductor coupling, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules.

Applicants believe that neither Ishihara nor Cox et al. disclose or suggest a method for coupling first and second microwave modules, comprising a first ground shield and a second ground shield that contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules. Inasmuch as claim 10 is in condition for allowance, claims 11 and 13 are believed to be in condition for allowance for at least those reasons. Accordingly, allowance of claims 11 and 13 is respectfully requested.

Claims 17 and 19 depend directly from independent claim 16. As discussed above, independent claim 16 calls for a method for coupling first and second microwave modules, wherein each microwave module comprises i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; and wherein, for each microwave module, at least the second dielectric and second ground shield are recessed from a first end of the conductor; wherein, for each microwave module, the first ground shield and the second ground shield contact one another to surround the first dielectric and the second dielectric at in a direction transverse to the conductor; the method comprising for each of the microwave modules, cutting the microwave module in proximity to the first end of the conductor, thereby defining a first edge of the microwave module; mounting the microwave modules adjacent one another, with their first edges facing each other; electrically coupling said first ends of the conductors of the microwave modules; and placing a ground shield cap over the conductor coupling, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules.

Applicants believe that neither Ishihara nor Cox et al. disclose or suggest a method comprising the first ground shield and the second ground shield contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules. Inasmuch as claim 16 is believed to be in condition for allowance, claims 17 and 19 are believed to be in condition for allowance for at least those reasons. Accordingly, allowance of claims 17 and 19 is respectfully requested.

13. Rejection of Claim 3 Under 35 U.S.C. 103(a)

Claim 3 stands rejected under 35 U.S.C. 103(a) as being unpatentable over Ishihara in view of Drapeau et al. (U.S. Patent No. 6,307,446; hereinafter "Drapeau et al.").

Claim 3 depends directly from independent claim 1. As discussed hereinabove, independent claim 1 calls for a microwave circuit comprising first and second microwave modules, each of which comprises a conductor sandwiched between upper and lower thickfilm dielectrics, and a ground shield surrounding the upper and lower thickfilm dielectrics in a direction transverse to the conductor; wherein, at a first end of each of the conductors, the conductor extends from beneath its upper thickfilm dielectric to terminate at a cut edge of its microwave module; the microwave modules being mounted with said cut edges facing one another; a bridge conductor, electrically coupling the first ends of the conductors; and a ground shield cap, oriented over the bridge conductor and electrically coupled to the ground shield surrounding the upper and lower thickfilm dielectrics of each of the microwave modules.

Applicants believe that neither Ishihara nor Drapeau et al. disclose or suggest a ground shield that surrounds upper and lower thickfilm dielectrics and the conductor, and do not disclose or suggest a ground shield cap that is electrically coupled to a ground shield surrounding upper and lower thickfilm dielectrics. Inasmuch as claim 1 is believed to be in condition for allowance, claim 3 is believed to be in condition for at least those reasons. Accordingly, allowance of claim 3 is respectfully requested.

14. Rejection of Claims 12 and 18 Under 35 U.S.C. 103(a)

Claims 12 and 18 stand rejected under 35 U.S.C. 103(a) as being unpatentable over the rejection of Item 4 above as applied to claims 10 and 16, and further in view of Drapeau et al.

Claim 12 depends directly from independent claim 10. As discussed above, independent claim 10 calls for a method for coupling first and second microwave modules, wherein each microwave module comprises i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; and wherein, for each microwave module, at least the second dielectric and second ground shield are recessed from a first end of the conductor; wherein, for each microwave module, the first ground shield and the second ground shield contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor; the method comprising for each of the microwave modules, cutting the microwave module in proximity to the first end of the conductor, thereby defining a first edge of the microwave module; mounting the microwave modules adjacent one another, with their first edges facing each other; electrically coupling said first ends of the conductors of the microwave modules; and placing a ground shield cap over the conductor coupling, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules.

Applicants believe that neither Ishihara nor Drapeau et al. disclose or suggest a method for coupling first and second microwave modules, comprising a first ground shield and a second ground shield that contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules. Inasmuch as claim 10 is in condition for allowance, claim 12 is believed to be in condition for allowance for at least those reasons. Accordingly, allowance of claim 12 is respectfully requested.

Claim 18 depends directly from independent claim 16. As discussed above, independent claim 16 calls for a method, comprising selecting first and second microwave modules, each comprising i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; wherein, for each microwave module, at least the second dielectric and second ground shield are recessed from an end of the conductor terminating at or near a cut edge of the

microwave module; wherein, for each microwave module, the first ground shield and the second ground shield contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor; mounting the microwave modules adjacent one another, with said cut edge of the first microwave module facing said cut edge of the second microwave module; electrically coupling said ends of the conductors of the microwave modules; and placing a ground shield cap over the conductor coupling, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules.

Applicants believe that neither Ishihara nor Drapeau et al. disclose or suggest a method comprising the first ground shield and the second ground shield contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules. Inasmuch as claim 10 is believed to be in condition for allowance, claim 18 is believed to be in condition for allowance for at least those reasons. Accordingly, allowance of claim 18 is respectfully requested.

15. Rejection of Claims 5-8 Under 35 U.S.C. 103(a)

Claims 5-8 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Ishihara in view of Dove et al. '979 (U.S. Patent No. 6,457,979; hereinafter "Dove et al. '979").

Claims 5-8 each depend directly from independent claim 1. As discussed hereinabove, independent claim 1 calls for a microwave circuit comprising first and second microwave modules, each of which comprises a conductor sandwiched between upper and lower thickfilm dielectrics, and a ground shield surrounding the upper and lower thickfilm dielectrics in a direction transverse to the conductor; wherein, at a first end of each of the conductors, the conductor extends from beneath its upper thickfilm dielectric to terminate at a cut edge of its microwave module; the microwave modules being mounted with said cut edges facing one another; a bridge conductor, electrically coupling the first ends of the conductors; and a ground shield cap, oriented over the bridge conductor and electrically coupled

to the ground shield surrounding the upper and lower thickfilm dielectrics of each of the microwave modules.

Applicants believe that neither Ishihara nor Dove et al. '979 disclose or suggest a ground shield that surrounds upper and lower thickfilm dielectrics and the conductor, and do not disclose or suggest a ground shield cap that is electrically coupled to a ground shield surrounding upper and lower thickfilm dielectrics. Inasmuch as claim 1 is believed to be in condition for allowance, claims 5-8 are believed to be in condition for at least those reasons. Accordingly, allowance of claims 5-8 is respectfully requested.

16. Rejection of Claims 14, 15, 20 and 21 Under 35 U.S.C. 103(a)

Claims 14, 15, 20 and 21 stand rejected under 35 U.S.C. 103(a) as being unpatentable over the rejection of Item 4 above as applied to claims 10 and 16, and further in view of Dove et al. '979.

Claims 14 and 15 depend directly from independent claim 10. As discussed above, independent claim 10 calls for a method for coupling first and second microwave modules, wherein each microwave module comprises i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; and wherein, for each microwave module, at least the second dielectric and second ground shield are recessed from a first end of the conductor; wherein, for each microwave module, the first ground shield and the second ground shield contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor; the method comprising for each of the microwave modules, cutting the microwave module in proximity to the first end of the conductor, thereby defining a first edge of the microwave module; mounting the microwave modules adjacent one another, with their first edges facing each other; electrically coupling said first ends of the conductors of the microwave modules; and placing a ground shield cap over the conductor coupling, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules.

Applicants believe that neither Ishihara nor Dove et al. '979 disclose or suggest a method for coupling first and second microwave modules, comprising a first ground shield and a second ground shield that contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules. Inasmuch as claim 10 is in condition for allowance, claims 14 and 15 are believed to be in condition for allowance for at least those reasons. Accordingly, allowance of claims 14 and 15 is respectfully requested.

Claims 20 and 21 depend directly from independent claim 16. As discussed above, independent claim 16 calls for a method, comprising selecting first and second microwave modules, each comprising i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; wherein, for each microwave module, at least the second dielectric and second ground shield are recessed from an end of the conductor terminating at or near a cut edge of the microwave module; wherein, for each microwave module, the first ground shield and the second ground shield contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor; mounting the microwave modules adjacent one another, with said cut edge of the first microwave module facing said cut edge of the second microwave module; electrically coupling said ends of the conductors of the microwave modules; and placing a ground shield cap over the conductor coupling, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules.

Applicants believe that neither Ishihara nor Dove et al. '979 disclose or suggest a method comprising the first ground shield and the second ground shield contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules. Inasmuch as claim 16 is believed to be in condition for allowance, claims 20 and 21 are believed to be in condition for allowance for at least those reasons. Accordingly, allowance of claims 17 and 19 is respectfully requested.

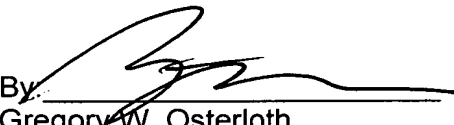
17. New Claims 22-25

Applicants have now added new claims 22-25, which depend from independent claims 1, 9, 10 and 16, respectively. No new matter has been added. Inasmuch as claims 22-25 depend directly from independent claims 1, 9, 10 and 16, respectively, Applicants believe that claims 22-25 are in condition for allowance for at least the above-identified reasons for the respective base claims. Accordingly, allowance if claims 22-25 is respectfully requested.

Conclusion

In light of the amendments and remarks provided herein, applicants respectfully request the timely issuance of a Notice of Allowance.

Respectfully submitted,
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